Low-Voltage 1.8/2.5/3.3 V 16-Bit Transparent Latch

With 3.6 V-Tolerant Inputs and Outputs (3-State, Non-Inverting)

The 74VCXH16373 is an advanced performance, non-inverting 16-bit transparent latch. It is designed for very high-speed, very low-power operation in 1.8 V, 2.5 V or 3.3 V systems. The VCXH16373 is byte controlled, with each byte functioning identically, but independently. Each byte has separate Output Enable and Latch Enable inputs. These control pins can be tied together for full 16-bit operation.

When operating at 2.5 V (or 1.8 V) the part is designed to tolerate voltages it may encounter on either inputs or outputs when interfacing to 3.3 V busses. It is guaranteed to be overvoltage tolerant to 3.6 V.

The 74VCXH16373 contains 16 D-type latches with 3-state 3.6 V-tolerant outputs. When the Latch Enable (LEn) inputs are HIGH, data on the Dn inputs enters the latches. In this condition, the latches are transparent, (a latch output will change state each time its D input changes). When LE is LOW, the latch stores the information that was present on the D inputs a setup time preceding the HIGH-to-LOW transition of LE. The 3-state outputs are controlled by the Output Enable (\overline{OEn}) inputs. When \overline{OE} is LOW, the outputs are enabled. When \overline{OE} is HIGH, the standard outputs are in the high impedance state, but this does not interfere with new data entering into the latches. The data inputs include active bushold circuitry, eliminating the need for external pullup resistors to hold unused or floating inputs at a valid logic state.

Features

- Designed for Low Voltage Operation: $V_{CC} = 1.65 \text{ V} 3.6 \text{ V}$
- 3.6 V Tolerant Inputs and Outputs
- High Speed Operation: 3.0 ns max for 3.0 V to 3.6 V

3.9 ns max for 2.3 V to 2.7 V

6.8 ns max for 1.65 V to 1.95 V

• Static Drive: ±24 mA Drive at 3.0 V

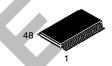
±18 mA Drive at 2.3 V ±6 mA Drive at 1.65 V

- Supports Live Insertion and Withdrawal
- Includes Active Bushold to Hold Unused or Floating Inputs at a Valid Logic State
- I_{OFF} Specification Guarantees High Impedance When $V_{CC} = 0 V^*$
- Near Zero Static Supply Current in All Three Logic States (20 μA) Substantially Reduces System Power Requirements
- Latchup Performance Exceeds ±250 mA @ 125°C
- ESD Performance: Human Body Model >2000 V Machine Model >200 V
- Pb-Free Package is Available**
- *To ensure the outputs activate in the 3–state condition, the output enable pins should be connected to V_{CC} through a pull–up resistor. The value of the resistor is determined by the current sinking capability of the output connected to the $\overline{\text{OE}}$ pin.



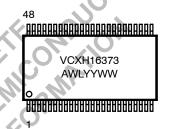
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TSSOP-48 DT SUFFIX CASE 1201

MARKING DIAGRAM



A = Assembly Location

WL = Wafer Lot YY = Year WW = Work Week

PIN NAMES

Pins	Function
OEn	Output Enable Inputs
LEn	Latch Enable Inputs
D0-D15	Inputs
O0-O15	Outputs

ORDERING INFORMATION

Device	Package	Shipping [†]
74VCXH16373DT	TSSOP	39 / Rail
74VCXH16373DTR	TSSOP	2500/Tape & Reel
74VCXH16373DTRG	TSSOP (Pb-Free)	2500/Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

^{**}For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

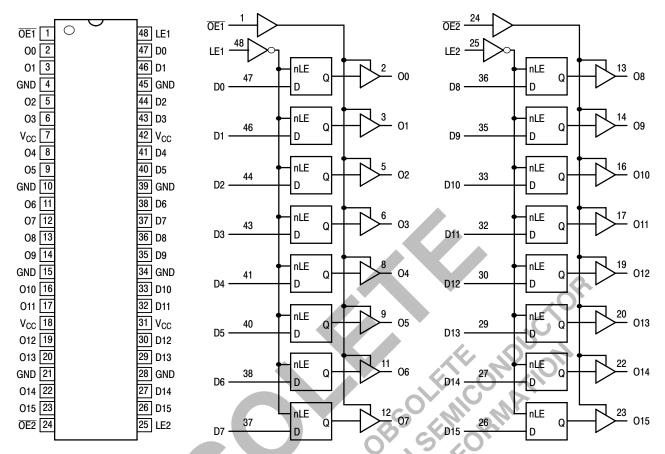


Figure 1. 48-Lead Pinout (Top View)

Figure 2. Logic Diagram

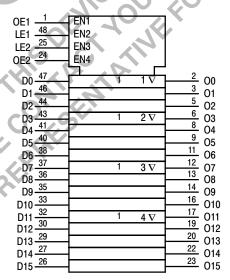


Figure 3. IEC Logic Diagram

TRUTH TABLE

	Inputs		Outputs		Inputs		Outputs
LE1	OE1	D0:7	O0:7	LE2	OE2	D8:15	O8:15
Х	Н	Х	Z	Х	Н	Х	Z
Н	L	L	L	Н	L	L	L
Н	L	Н	Н	Н	L	Н	Н
L	L	Х	00	L	L	Х	00

H = High Voltage Level

ABSOLUTE MAXIMUM RATINGS

Symbol	Parameter	Value	Condition	Unit
V _{CC}	DC Supply Voltage	-0.5 to +4.6	40%	V
VI	DC Input Voltage	$-0.5 \le V_{ } \le +4.6$		V
Vo	DC Output Voltage	$-0.5 \le V_0 \le +4.6$	Output in 3-State	V
		$-0.5 \le V_{O} \le V_{CC} + 0.5$	Note 1; Outputs Active	٧
I _{IK}	DC Input Diode Current	-50	V _L < GND	mA
I _{OK}	DC Output Diode Current	-50	V _O < GND	mA
		+50	V _O > V _{CC}	mA
Io	DC Output Source/Sink Current	±50	, O,	mA
Icc	DC Supply Current Per Supply Pin	±100		mA
I _{GND}	DC Ground Current Per Ground Pin	±100		mA
T _{STG}	Storage Temperature Range	−65 to +150		°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

1. I_O absolute maximum rating must be observed.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Min	Тур	Max	Unit
V _{CC}	Supply Voltage Operati Data Retention Or	J	3.3 3.3	3.6 3.6	V
VI	Input Voltage	-0.3		3.6	V
V _O	Output Voltage (Active States) (3–States)	,		V _{CC} 3.6	V
I _{OH}	HIGH Level Output Current, V _{CC} = 3.0 V - 3.6 V			-24	mA
I _{OL}	LOW Level Output Current, V _{CC} = 3.0 V - 3.6 V			24	mA
I _{OH}	HIGH Level Output Current, V _{CC} = 2.3 V - 2.7 V			-18	mA
I _{OL}	LOW Level Output Current, V _{CC} = 2.3 V - 2.7 V			18	mA
I _{OH}	HIGH Level Output Current, V _{CC} = 1.65 V - 1.95 V			-6	mA
I _{OL}	LOW Level Output Current, V _{CC} = 1.65 V - 1.95 V			6	mA
T _A	Operating Free-Air Temperature	-40		+85	°C
$\Delta t/\Delta V$	Input Transition Rise or Fall Rate, V_{IN} from 0.8 V to 2.0 V, V_{CC} = 3.0 V	0		10	ns/V

L = Low Voltage Level

Z = High Impedance State

X = High or Low Voltage Level and Transitions Are Acceptable, for I_{CC} reasons, DO NOT FLOAT Inputs.

O0 = No Change.

DC ELECTRICAL CHARACTERISTICS

			T _A = -40°0	C to +85°C	
Symbol	Characteristic	Condition	Min	Max	Unit
V _{IH}	HIGH Level Input Voltage (Note 2)	1.65 V ≤ V _{CC} < 2.3 V	0.65 x V _{CC}		٧
		2.3 V ≤ V _{CC} ≤ 2.7 V	1.6		1
		2.7 V < V _{CC} ≤ 3.6 V	2.0		1
V _{IL}	LOW Level Input Voltage (Note 2)	1.65 V ≤ V _{CC} < 2.3 V		0.35 x V _{CC}	V
		2.3 V ≤ V _{CC} ≤ 2.7 V		0.7	1
		2.7 V < V _{CC} ≤ 3.6 V		0.8	1
V _{OH}	HIGH Level Output Voltage	1.65 V ≤ V_{CC} ≤ 3.6 V; I_{OH} = -100 μ A	V _{CC} - 0.2		V
		V _{CC} = 1.65 V; I _{OH} = -6 mA	1.25		1
		V _{CC} = 2.3 V; I _{OH} = -6 mA	2.0		1
		V _{CC} = 2.3 V; I _{OH} = -12 mA	1.8		1
		V _{CC} = 2.3 V; I _{OH} = -18 mA	1.7	0	1
		$V_{CC} = 2.7 \text{ V; } I_{OH} = -12 \text{ mA}$	2.2	.0	1
		V _{CC} = 3.0 V; I _{OH} = -18 mA	2.4		1
		V _{CC} = 3.0 V; I _{OH} = -24 mA	2.2	<u> </u>	1
V _{OL}	LOW Level Output Voltage	$1.65 \text{ V} \le \text{V}_{CC} \le 3.6 \text{ V}; \text{I}_{OL} = 100 \mu\text{A}$, ,(0)	0.2	V
		V _{CC} = 1.65 V; I _{OL} = 6 mA		0.3	1
		$V_{CC} = 2.3 \text{ V; } I_{OL} = 12 \text{ mA}$		0.4	1
		V _{CC} = 2.3 V; I _{OL} = 18 mA	ellin	0.6	1
		$V_{CC} = 2.7 \text{ V; } I_{OL} = 12 \text{ mA}$	181	0.4	1
		$V_{CC} = 3.0 \text{ V; } I_{OL} = 18 \text{ mA}$)	0.4	1
		$V_{CC} = 3.0 \text{ V; } I_{OL} = 24 \text{ mA}$		0.55	1
I _I	Input Leakage Current	$1.65 \text{ V} \le \text{V}_{CC} \le 3.6 \text{ V}; \text{ 0V} \le \text{V}_{\text{I}} \le 3.6 \text{ V}$		±5.0	μА
I _{I(HOLD)}	Minimum Bushold Input Current	V _{CC} = 3.0 V, V _{IN} = 0.8 V	75		μА
,		$V_{CC} = 3.0 \text{ V}, V_{IN} = 2.0 \text{ V}$	-75		1
		$V_{CC} = 2.3 \text{ V}, V_{IN} = 0.7 \text{ V}$	45		1
		V _{CC} = 2.3 V, V _{IN} = 1.6 V	-45		1
		V _{CC} = 1.65 V, V _{IN} = 0.57 V	25		1
		V _{CC} = 1.65 V, V _{IN} = 1.07 V	-25		1
I _{I (OD)}	Minimum Bushold Over-Drive	V _{CC} = 3.6 V, (Note 3)	450		μА
. (02)	Current Needed to Change State		-450		1
	6	V _{CC} = 2.7 V, (Note 3)	300		1
	Current Needed to Change State	V _{CC} = 2.7 V, (Note 4)	-300		1
		V _{CC} = 1.95 V, (Note 3)	200		1
	Q Y	V _{CC} = 1.95 V, (Note 4)	-200		1
I _{OZ}	3-State Output Current	$1.65 \text{ V} \le \text{V}_{CC} \le 3.6 \text{ V}; 0 \text{ V} \le \text{V}_{O} \le 3.6 \text{ V};$ $\text{V}_{I} = \text{V}_{IH} \text{ or V}_{IL}$		±10	μΑ
I _{OFF}	Power-Off Leakage Current	V _{CC} = 0 V; V _I or V _O = 3.6 V		10	μА
I _{CC}	Quiescent Supply Current (Note 5)	1.65 V ≤ V _{CC} ≤ 3.6 V; V _I = GND or V _{CC}		20	μΑ
50]	1.65 V ≤ V _{CC} ≤ 3.6 V; 3.6 V ≤ V _I , V _O ≤ 3.6 V		±20	μA
		, , ,		1	

These values of V_I are used to test DC electrical characteristics only.
 An external driver must source at least the specified current to switch from LOW-to-HIGH.
 An external driver must source at least the specified current to switch from HIGH-to-LOW.
 Outputs disabled or 3-state only.

AC CHARACTERISTICS (Note 6; t_R = t_F = 2.0 ns; C_L = 30 pF; R_L = 500 Ω)

					$T_A = -40$	0°C to +85°	С		
			V _{CC} = 3.0	V to 3.6 V	V _{CC} = 2.3	V to 2.7 V	V _{CC} = 1.65	V to 1.95 V	
Symbol	Parameter	Waveform	Min	Max	Min	Max	Min	Max	Unit
t _{PLH} t _{PHL}	Propagation Delay Dn-to-On	1	0.8 0.8	3.0 3.0	1.0 1.0	3.4 3.4	1.5 1.5	6.8 6.8	ns
t _{PLH} t _{PHL}	Propagation Delay LE-to-On	1	0.8 0.8	3.0 3.0	1.0 1.0	3.9 3.9	1.5 1.5	7.8 7.8	ns
t _{PZH}	Output Enable Time to High and Low Level	2	0.8 0.8	3.5 3.5	1.0 1.0	4.6 4.6	1.5 1.5	9.2 9.2	ns
t _{PHZ}	Output Disable Time From High and Low Level	2	0.8 0.8	3.5 3.5	1.0 1.0	3.8 3.8	1.5 1.5	6.8 6.8	ns
t _s	Setup Time, High or Low Dn-to-LE	3	1.5		1.5		2.5		ns
t _h	Hold Time, High or Low Dn-to-LE	3	1.0		1.0		1.0	0	ns
t _w	LE Pulse Width, High	3	1.5		1.5		4.0	Э,	ns
t _{OSHL} t _{OSLH}	Output-to-Output Skew (Note 7)			0.5 0.5		0.5 0.5	110	0.75 0.75	ns

^{6.} For $C_L = 50$ pF, add approximately 300 ps to the AC maximum specification.

AC CHARACTERISTICS (t_R = t_F = 2.0 ns; C_L = 50 pF; R_L = 500 Ω)

				T _A = -40°C to +85°	С		
			V _{CC} = 3.0	V to 3.6 V	V _{CC} =	: 2.7 V	
Symbol	Parameter	Waveform	Min	Max	Min	Max	Unit
t _{PLH} t _{PHL}	Propagation Delay Dn-to-On	4	1.0 1.0	3.6 3.6		4.3 4.3	ns
t _{PLH} t _{PHL}	Propagation Delay LE-to-On	4	1.0 1.0	3.9 3.9		4.6 4.6	ns
t _{PZH} t _{PZL}	Output Enable Time to High and Low Level	5	1.0 1.0	4.7 4.7		5.7 5.7	ns
t _{PHZ}	Output Disable Time From High and Low Level	5	1.0 1.0	4.1 4.1		4.5 4.5	ns
t _{OSHL} t _{OSLH}	Output-to-Output Skew (Note 8)	4 0		0.5 0.5		0.5 0.5	ns

Skew is defined as the absolute value of the difference between the actual propagation delay for any two separate outputs of the same device.
 The specification applies to any outputs switching in the same direction, either HIGH-to-LOW (t_{OSHL}) or LOW-to-HIGH (t_{OSLH}); parameter guaranteed by design.

Skew is defined as the absolute value of the difference between the actual propagation delay for any two separate outputs of the same device.
 The specification applies to any outputs switching in the same direction, either HIGH-to-LOW (t_{OSHL}) or LOW-to-HIGH (t_{OSLH}); parameter guaranteed by design.

DYNAMIC SWITCHING CHARACTERISTICS

			T _A = +25°C	
Symbol	Characteristic	Condition	Тур	Unit
V _{OLP}	Dynamic LOW Peak Voltage	V_{CC} = 1.8 V, C_L = 30 pF, V_{IH} = V_{CC} , V_{IL} = 0 V	0.25	V
	(Note 9)	V_{CC} = 2.5 V, C_L = 30 pF, V_{IH} = V_{CC} , V_{IL} = 0 V	0.6	
		V_{CC} = 3.3 V, C_L = 30 pF, V_{IH} = V_{CC} , V_{IL} = 0 V	0.8	
V _{OLV}	Dynamic LOW Valley Voltage	V_{CC} = 1.8 V, C_L = 30 pF, V_{IH} = V_{CC} , V_{IL} = 0 V	-0.25	V
	(Note 9)	V_{CC} = 2.5 V, C_L = 30 pF, V_{IH} = V_{CC} , V_{IL} = 0 V	-0.6	
		V_{CC} = 3.3 V, C_L = 30 pF, V_{IH} = V_{CC} , V_{IL} = 0 V	-0.8	
V _{OHV}	Dynamic HIGH Valley Voltage	V _{CC} = 1.8 V, C _L = 30 pF, V _{IH} = V _{CC} , V _{IL} = 0 V	1.5	V
	(Note 10)	V_{CC} = 2.5 V, C_L = 30 pF, V_{IH} = V_{CC} , V_{IL} = 0 V	1.9	
		V_{CC} = 3.3 V, C_L = 30 pF, V_{IH} = V_{CC} , V_{IL} = 0 V	2.2	7

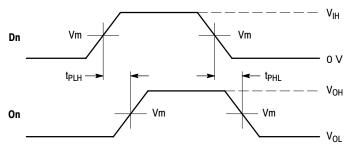
^{9.} Number of outputs defined as "n". Measured with "n-1" outputs switching from HIGH-to-LOW or LOW-to-HIGH. The remaining output is measured in the LOW state.

CAPACITIVE CHARACTERISTICS

Symbol	Parameter	Condition Typical	Unit
C _{IN}	Input Capacitance	Note 11 6	pF
C _{OUT}	Output Capacitance	Note 11 7	pF
C _{PD}	Power Dissipation Capacitance	Note 11, 10 MHz 20	pF

 $[\]overline{11. V_{CC}} = 1.8 \text{ V}, 2.5 \text{ V or } 3.3 \text{ V}; V_{I} = 0 \text{ V or } V_{CC}.$

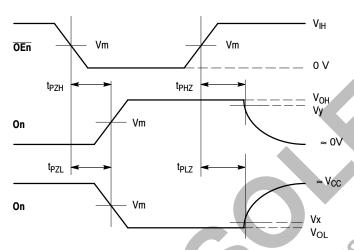
^{10.} Number of outputs defined as "n". Measured with "n-1" outputs switching from HIGH-to-LOW or LOW-to-HIGH. The remaining output is measured in the HIGH state.



WAVEFORM 1 - PROPAGATION DELAYS

 t_R = t_F = 2.0 ns, 10% to 90%; f = 1 MHz; t_W = 500 ns

Figure 4. AC Waveforms



WAVEFORM 2 – OUTPUT ENABLE AND DISABLE TIMES $t_R = t_F = 2.0 \text{ ns}, 10\% \text{ to } 90\%; f = 1 \text{ MHz}; t_W = 500 \text{ ns}$

WAVEFORM 3 – LE to On PROPAGATION DELAYS, LE MINIMUM PULSE WIDTH, Dn to LE SETUP AND HOLD TIMES

 $t_R = t_F = 2.0$ ns, 10% to 90%; f = 1 MHz; $t_W = 500$ ns except when noted

Figure 5. AC Waveforms

Table 1. AC WAVEFORMS

	9', C',	V _{CC}	
Symbol	3.3 V ± 0.3 V	2.5 V ± 0.2 V	1.8 V ± 0.15 V
V _{IH}	2.7 V	V _{CC}	V _{CC}
V _m	1.5 V	V _{CC} /2	V _{CC} /2
V _x	V _{OL} + 0.3 V	V _{OL} + 0.15 V	V _{OL} + 0.15 V
Vy	V _{OH} – 0.3 V	V _{OH} – 0.15 V	V _{OH} – 0.15 V

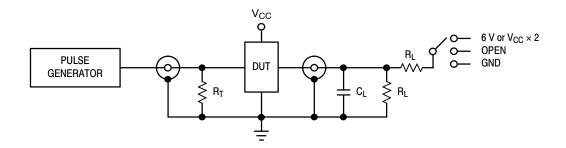
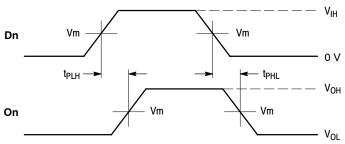


Figure 6. Test Circuit

Table 2. TEST CIRCUIT

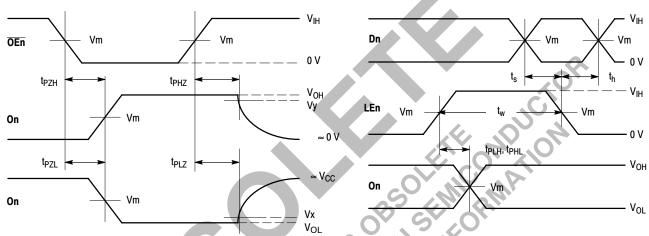
	SWITCH
PLH, tPHL	Open
PZL, †PLZ	6 V at V_{CC} = 3.3 ± 0.3 V; $V_{CC} \times$ 2 at V_{CC} = 2.5 ± 0.2 V; 1.8 ± 0.15 V
^t PZH, ^t PHZ	GND
PIERSE PREPAR	$6 V \text{ at } V_{CC} = 3.3 \pm 0.3 \text{ V};$ $V_{CC} \times 2 \text{ at } V_{CC} = 2.5 \pm 0.2 \text{ V}; 1.8 \pm 0.15 \text{ V}$ GND ig and probe capacitance) cally 50 Ω)



WAVEFORM 4 - PROPAGATION DELAYS

 $t_R = t_F = 2.0 \text{ ns}, 10\% \text{ to } 90\%; f = 1 \text{ MHz}; t_W = 500 \text{ ns}$

Figure 7. AC Waveforms



WAVEFORM 5 - OUTPUT ENABLE AND DISABLE TIMES $t_R = t_F = 2.0 \text{ ns}, 10\% \text{ to } 90\%; f = 1 \text{ MHz}; t_W = 500 \text{ ns}$

WAVEFORM 6 - LE to On PROPAGATION DELAYS, LE MINIMUM PULSE WIDTH, Dn-to-LE SETUP AND HOLD TIMES

 $t_R = t_F = 2.0$ ns, 10% to 90%; f = 1 MHz; $t_W = 500$ ns except when noted

Figure 8. AC Waveforms

Table 3. AC WAVEFORMS

	V _C	cc
Symbol	3.3 V ± 0.3 V	2.7 V
V _{IH}	2.7 V	2.7 V
V _m	1.5 V	1.5 V
V _x	V _{OL} + 0.3 V	V _{OL} + 0.3 V
V_{v}	V _{OH} – 0.3 V	V _{OH} – 0.3 V

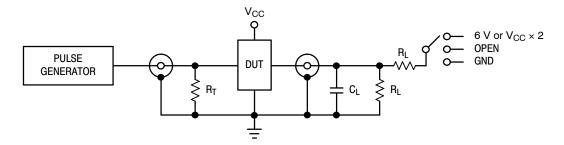


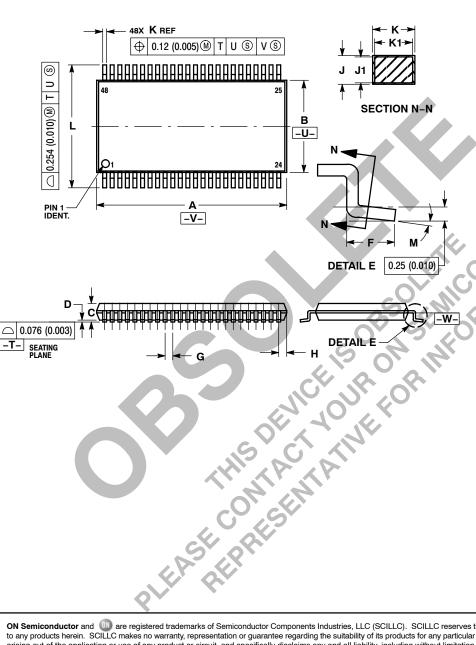
Figure 9. Test Circuit

Table 4. TEST CIRCUIT

TEST	SWITCH		
PLH, ^t PHL	Open		
_{PZL} , t _{PLZ}	6 V at V_{CC} = 3.3 ± 0.3 V; $V_{CC} \times$ 2 at V_{CC} = 2.5 ± 0.2 V; 1.8 ± 0.15 V		
PZH, [†] PHZ	GND		
C_L = 50 pF or equivalent (Includes jig and R_L = 500 Ω or equivalent R_T = Z_{OUT} of pulse generator (typically 50	Open $6 \text{ V at } V_{CC} = 3.3 \pm 0.3 \text{ V};$ $V_{CC} \times 2 \text{ at } V_{CC} = 2.5 \pm 0.2 \text{ V}; 1.8 \pm 0.15 \text{ V}$ $\boxed{\text{GND}}$ $\boxed{\text{probe capacitance}}$ $\boxed{\Omega}$		

PACKAGE DIMENSIONS

TSSOP DT SUFFIX CASE 1201-01 **ISSUE A**



NOTES:

- 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- CONTROLLING DIMENSION: MILLIMETER.
 DIMENSIONS A AND B DO NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.

 4. DIMENSION K DOES NOT INCLUDE DAMBAR
- PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION
- TERMINAL NUMBERS ARE SHOWN FOR
- REFERENCE ONLY.
 DIMENSIONS A AND B ARE TO BE DETERMINED AT DATUM PLANE -W-

	MILLIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
Α	12.40	12.60	0.488	0.496
В	6.00	6.20	0.236	0.244
C		1.10		0.043
D	0.05	0.15	0.002	0.006
F	0.50	0.75	0.020	0.030
G	0.50 BSC		0.0197 BSC	
Η,	0.37		0.015	
7	0.09	0.20	0.004	0.008
J1	0.09	0.16	0.004	0.006
K	0.17	0.27	0.007	0.011
K1	0.17	0.23	0.007	0.009
L	7.95	8.25	0.313	0.325
M	0 °	8 °	0 °	8°

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